Open Discussion – Interacting Standards

- IBIS 8.0 (Active Standard)
  - Supports “IBIS Interconnect” for packages, “EMD” for modules
  - Links to IBIS-ISS, Touchstone
- IBIS-ISS 1.0 (Active Standard)
  - Standardizes passive SPICE for interconnects
- Touchstone 3.0 (Pre-Draft)
  - Will support pole-residue, clarified referencing, port-mapping
- IEEE 2401 “LPB” (Active Standard; driven by JEITA)
  - Unifies netlist, design rule, geometry, and other data for an entire project
  - Links to IBIS, IBIS-ISS, and Touchstone formats
- IEEE 3537 (Draft)
  - Language for advanced packaging, describing physical properties and design rules for 2.5/3D structures, and the connectivity between them

How do we manage interactions between these standards as they evolve?

How best can we inform industry users to learn and try these formats?

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